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Thank you for attending the 67th ECTC!

I would like to thank all authors, presenters, program committee members, exhibitors, sponsors, volunteers, and all attendees for making the 67th ECTC one of the most successful events in our 67 year history.

Here are some conference statistics:

- 1,439 attendees, the third highest attendance ever and highest attendance at the Orlando, FL, USA location
- Attendees came from 22 different countries
- 337 technical papers, presented in 36 oral and five interactive presentation sessions, including a student interactive presentation session
- 44 sponsorships - a new record
- 18 professional development courses attended by 473 participants - another new record
- 110 Technology Corner booths - a record number with most exhibitors already committed to return next year!

In addition to the regular daytime sessions and courses, we offered six additional special sessions including three special sessions on Tuesday afternoon and three evening seminars that were all very well attended:

- ECTC Panel Session
 - Co-chaired by CPMT President Jean Trehwella of GLOBALFOUNDRIES and Young Gon Kim of Integrated Device Technology on panel fan-out manufacturing
- ECTC Plenary Session
 - Chaired by Luke England of GLOBALFOUNDRIES on packaging for autonomous vehicle electronics
- CPMT Seminar
 - Co-chaired by Venky Sundaram of the Georgia Institute of Technology and Yasumitsu Orii of Nagase, Japan, on 3D printing
- Applied Reliability Special Session
 - Co-chaired by Vikas Gupta of Texas Instruments and Pradeep Lall of Auburn University on material and package reliability challenges for harsh environments
- ECTC Special Session
 - Chaired by Bing Dang of IBM Corporation on flexible hybrid electronics
- 3rd CPMT Women's Panel
 - Chaired by Kitty Pearsall of Boss Precision, Inc., on emotional intelligence (EI) - link to successful leadership

Finally, thank you to the ECTC Keynote Speaker, Dr. Babak Sabi, Corporate Vice

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ECTC 2017 Program



The technical program is [available online](#)

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President and Director of Assembly and Test Technology Development of Intel Corporation who gave a very well-received presentation on "Advanced Packaging in the New World of Data." Babak explained that heterogeneous integration will play a key role going forward.

I would like to thank our corporate sponsors - particularly our Gold Gala sponsors Amkor, Cadence, Deca Technologies, Dow Electronic Materials, Lintec, Nanium, PacTech, SPTS, and Unity; our Silver Gala Sponsors Applied Materials, IBM, Micron, SPIL, Süss, Veeco, and Zeiss; and additional Special and Program sponsors.

Photos taken at the conference are now available on [Flickr](#).

The 2018 conference will be held 29 May-1 June 2018, at the Sheraton San Diego Hotel and Marina, San Diego, CA, USA.

San Diego is a great venue and I hope to see you there!

Best Regards,

Henning Braunisch, Ph.D., FIEEE
General Chair, 67th Electronic Components and Technology Conference
Intel Corporation

For more information on the 2017 ECTC visit www.ectc.net.
Also, see some of the ECTC 2016 [highlights](#).

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